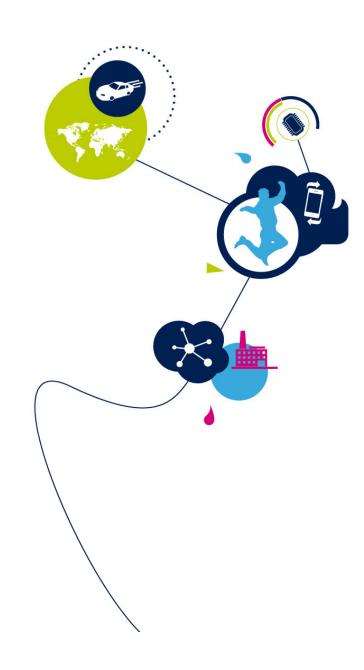


STMicroelectronics

February 26, 2019 Barcelona





Forward Looking Statements 2

Some of the statements contained in this release that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance, or events to differ materially from those anticipated by such statements, due to, among other factors:

- Uncertain macro-economic and industry trends, which may impact end-market demand for our products;
- Customer demand that differs from projections:
- The ability to design, manufacture and sell innovative products in a rapidly changing technological environment;
- Changes in economic, social, labor, political, or infrastructure conditions in the locations where we, our customers, or our suppliers operate, including as a result of macro-economic or regional events, military conflicts, social unrest. labor actions, or terrorist activities:
- Changes in global trade policies, including the adoption and expansion of tariffs and trade barriers, that could affect the macro-economic environment and adversely impact the demand for our products:
- The Brexit vote and the perceptions as to the impact of the withdrawal of the U.K. may adversely affect business activity, political stability and economic conditions in the U.K., the Eurozone, the EU and elsewhere. While we do not have material operations in the U.K. and have not experienced any material impact from Brexit on our underlying business to date, we cannot predict its future implications:
- Financial difficulties with any of our major distributors or significant curtailment of purchases by key customers;
- The loading, product mix, and manufacturing performance of our production facilities:
- The functionalities and performance of our IT systems, which support our critical operational activities including manufacturing, finance and sales, and any breaches of our IT systems or those of our customers or suppliers:
- Variations in the foreign exchange markets and, more particularly, the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;
- The impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions:
- Changes in our overall tax position as a result of changes in tax rules, new or revised legislation, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets:
- The outcome of ongoing litigation as well as the impact of any new litigation to which we may become a defendant;
- Product liability or warranty claims, claims based on epidemic or delivery failure, or other claims relating to our products, or recalls by our customers for products containing our parts;
- Natural events such as severe weather, earthquakes, tsunamis, volcano eruptions or other acts of nature, health risks and epidemics in locations where we, our customers or our suppliers operate;
- Availability and costs of raw materials, utilities, third-party manufacturing services and technology, or other supplies required by our operations;
- Industry changes resulting from vertical and horizontal consolidation among our suppliers, competitors, and customers;
- The ability to successfully ramp up new programs that could be impacted by factors beyond our control, including the availability of critical third party components and performance of subcontractors in line with our expectations: and
- Theft, loss, or misuse of personal data about our employees, customers, or other third parties, and breaches of global privacy legislation, including the EU's General Data Protection Regulation ("GDPR").

Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.

Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2017, as filed with the SEC on March 1, 2018. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed, or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.



Agenda

9:30 am

Introduction

ST Industrial End Market Approach

Automotive and Discrete Group (ADG)



Analog, MEMS & Sensors Group (AMS)



Microcontroller and Digital ICs Group (MDG)



Questions & Answers



11:00 am End



Speakers

Jean-Marc Chery President & CEO

Marco Cassis

President, Sales, Marketing, Communications & Strategy

Marco Monti President, ADG

Benedetto Vigna President, AMS

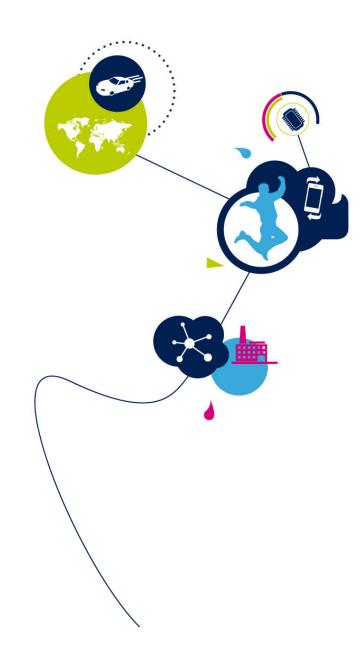
Claude Dardanne President, MDG

Introduction

Jean-Marc Chery

President & CEO



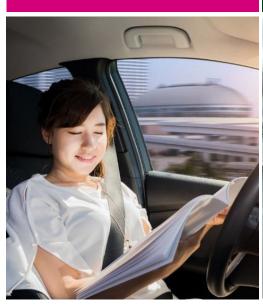


Automotive

Industrial

Personal Electronics

Communications Equipment, Computers & Peripherals













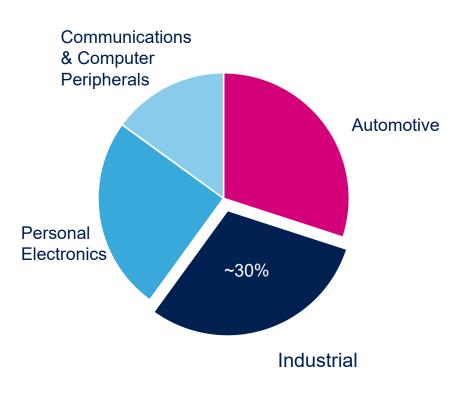
Marco Cassis

President
Sales, Marketing, Communications and Strategy Development





ST Industrial Sales ____







ST is a Top Player in Key Industrial Components

Rank	Industrial
1	Texas Instruments
2	Analog Devices
3	Intel
4	Infineon
5	STMicroelectronics

Rank	Analog IC
1	Texas Instruments
2	Analog Devices
3	STMicroelectronics

1 Intel 2 Texas Instruments 3 Microchip 4 STMicroelectronics	Rank	Microcomponents	
3 Microchip	1	Intel	
,	2	Texas Instruments	
4 STMicroelectronics	3	Microchip	
	4	STMicroelectronics	

Rank	Power Discretes
1	Infineon
2	STMicroelectronics

Rank	Sensors & Actuators
1	Analog Devices
8	STMicroelectronics











Source: IHS Markit - Q2 2018

ST Approach in Industrial

Technologies & Products

Differentiated specialized technologies adapted to device development

BCD

ViPower

eFlash FD-SOI 28nm

CMOS

SiC GaN

Power **MOSFETs** Processing

Security

Sensing & Actuating

Connectivity

Conditioning & Protection

> Motor Control

Power & Energy

Application Approach

Use deep industrial knowledge to develop solutions optimized for specific applications, combined with a broad general purpose portfolio



Market Approach

Target industry leaders with leadingedge products adapted to their needs









Target wider market with broad portfolio mainly through distribution





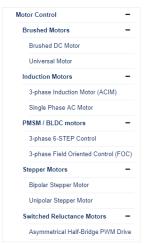




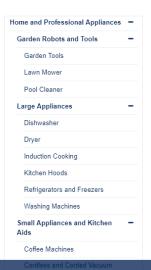
















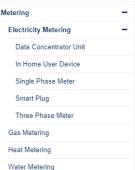


ST offers Products and Solutions for a wide range of industrial applications

PLC Control Unit
Safety PLC

Tracking –
Goods Guarantee
Pallets and Container Tracking

Metering –











Industrial Drives

Point of Sales and Retail Logistics **Banking Automation** Currency Counter USB NFC Dongles Point of Sales ePOS FCR and Cash Drawer Mobile POS Payment Dongles Retail Logistics Barcode Scanners Electronic Shelf Labels Goods Guarantee NFC HF Readers Pallets and Container Tracking Portable Data Terminals RAIN UHF Readers



ST Technology Investments for Industrial

Analog & RF CMOS	Specific focus on industrial applications in technology development
eNVM CMOS	Serves Microcontrollers for Industrial
FD-SOI CMOS FinFET through Foundry	Serves MPU & COT ASICs for Industrial
MEMS For Sensors & Microactuators	Leveraging investments in Personal Electronics

Specific focus on industrial applications in technology development	Smart Power: BCD
Specific focus on industrial applications in technology development	Discrete, Passive Integration, Power MOSFET, IGBT Silicon Carbide, Gallium Nitride
Leveraging investments in Automotive	Vertical Intelligent Power
Leveraging investments in Personal Electronics	Specialized Imaging Sensors

Packaging technologies

Specific investments for Industrial Power Modules e.g. ACEPACK, SLLIMM



ST Product Strategies for Industrial

Products Designed for Industrial

Dedicated Industrial products covering a major part of a specific application

e.g. Smart Metering SoC with full system support

Dedicated Industrial products for a specific function in a specific application

e.g. I/O Driver for Programmable Logic Controllers

Dedicated Industrial products for a specific function covering multiple applications

e.g. Motor Control ICs, Power Discrete, Industrial MPU

Products from other target markets adapted for industrial specifics

e.g. Industrial sensors offering 10 year guarantee



General Purpose/ Multi-Market Products for Industrial



General purpose products requiring application-specific support

e.g. STM32 for Motor Control, Metering

Products sold across multiple end markets

e.g. Wireless Connectivity, Security. ToF, EEPROM

Products from other target markets fitting with industrial applications

e.g. Automotive MCUs, ST60 RF mmW

General purpose products with no special support required

e.g. General Purpose Analog



New Products for Industrial Applications 13

Industrial MPU

New multicore STM32MP1 Series for Industrial and IoT applications







Industrial Safety

New safety-design package for STM32 MCUs





Smart Meters

STSAFE-J100 Certified and Flexible secure solution



Power Adapters

Power supplies & adapters are more reliable with new off-line converters





Condition Monitoring

High-accuracy MEMS accelerometer for advanced industrial sensing



Robotics

Industrial Magnetometer Reliable positioning and ranging











Factory Automation

Intelligent Power Switch rich diagnostics for Smart Industry





Logistics Tracking

Teseo-LIV3F module GNSS solution for Industrial and IoT



Building Automation

Tiny KNX transceiver for smart building automation



Power Supplies

Off-line high-voltage converters for rugged and flexible 5-30V power supplies





3D Printing

Plug-and-play STSPIN board for faster & smoother 3D printing





Medical Robots

Versatile motor drivers for industrial & medical applications





ST Go-To-Market Strategy for Industrial

Ecosystem to Support Design-in

Comprising hardware, software and documentation Pervasive **Technical** Support

FAEs and training on the field

Strong Online Presence

Product data. design tools and application support online

Promotion Campaigns

Raise brand awareness extend reach

Development with lead OEMs

Build IP to be reused in the broader market and vice versa

Distribution Channel

Leverage local expertise and support

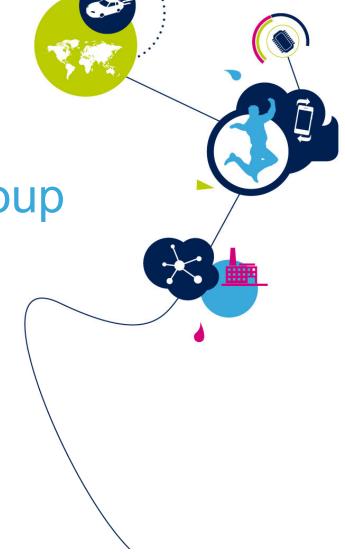


Automotive and Discrete Group

Marco Monti

President Automotive and Discrete Group (ADG)







Automotive and Discrete Group

2018 – Key Financial Figures







ADG by Sub-Group





ADG: 2018 Product Coverage

Radical Innovation anticipating market needs



Car Electrification SiC, GaN, IGBT, Modules, Galvanic Isolation, MCUs, **Battery Management**



Autonomous Driving Level 4-5 ASICs Auto-parking ASICs



Charging SiC, Diodes, IGBT, Modules



5G Base Station GaN-RF

Enabling Transformation emerging trends



Radar Rx/Tx, MCUs, Digital ASICs, Power Supply



Car Connectivity Telematic Processors, GNSS, V2X



48V System VIPower, LV MOSFETs, **ASICs**

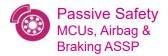


Automation SiC, IGBT, Modules

High Volume Applications gaining market share

~ 65% of ADG Revenues







Body MCUs, Door Control, Lighting



Power Supply HV MOSFET, Diodes Mobile Phone Protection, Filters





Conditioning SCR, IGBT, Modules







Industrial



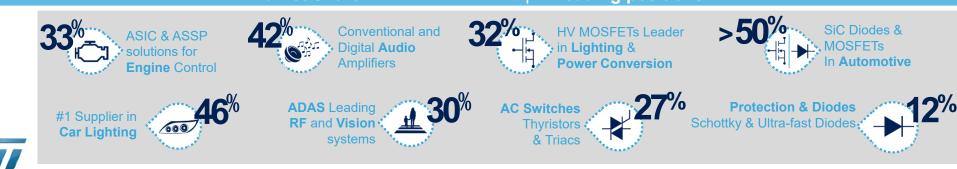
Personal Electronics & Communications

2018 Double-Digit Growth

Driven by Innovative Technologies

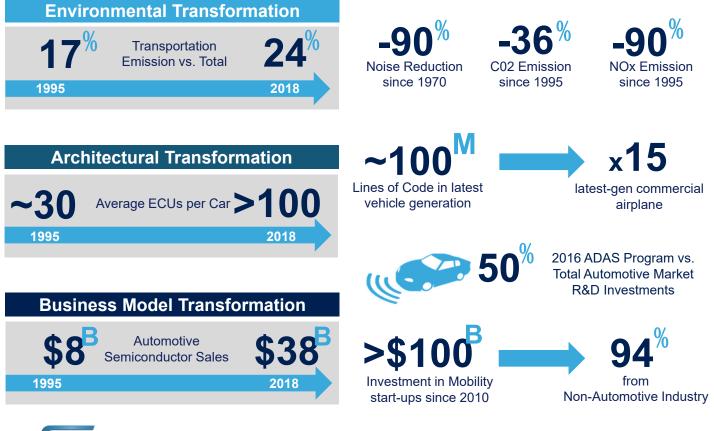
Automotive Product Sub-Group Power Discrete Sub-Group **Motor Control RF Power Solution Electric Power Steering** Voltage Suppressor **Power Distribution Integrated Filters** YoY Growth YoY Growth Lighting and Body **ADAS** Low Voltage MOSFET 32-bit Microcontroller **IGBT** Connectivity SiC YoY Growth YoY Growth **Premium Audio Amplifier Power Modules**

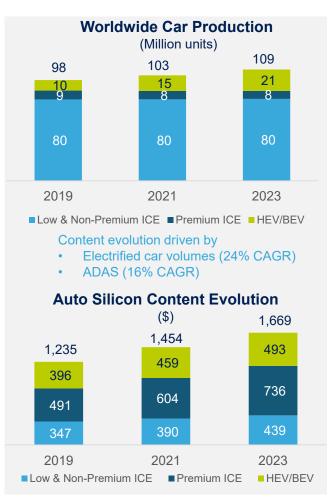
ST Market Share on some of our Multiple Leading positions:





Automotive Transformation 19







Source: Automotive news, McKinsey center of future mobility, Strategy Analytics, ST Internal

Automotive Smart Driving

Megatrend Convergence

Electric Vehicles

10cent/Km as mobility cost target

40% Electrified Vehicles by 2021

-35% CO2 by 2030

Zero Emission by 2040 in City Zero Net Emission by 2050

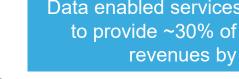
Multiple vehicle configurations to support multiple mobility needs (Hybrid, Plug in, Electric, Fuel cells...)





New Digital Architecture to Enable Software Reconfigurable vehicles









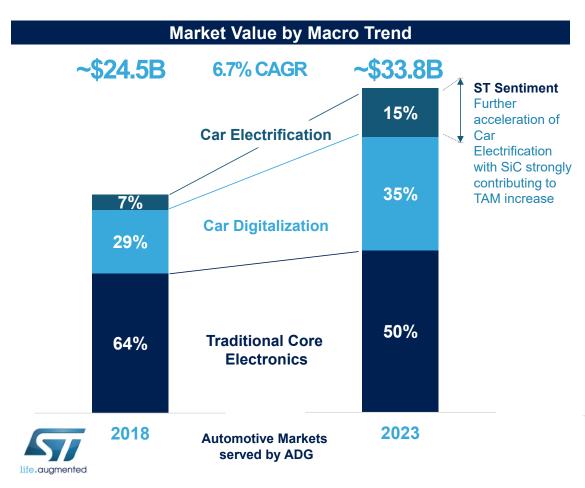




Supporting shared mobility by 2030 with one car in ten shared

Cheaper mobility proliferation with "Robo-taxis"

Automotive Semiconductor Market Outlook 21



ADG Group Ambitions

- Build on leadership position in traditional core automotive electronics
- Exceed the market growth in car digitalization focusing on:
 - 32-bit new Arm® Microcontroller generation (Stellar)
 - ADAS (vision, radar) and automated parking solutions
 - · Connectivity and Security
- Continued leadership in vehicle electrification with innovative automotive power solutions (Si, SiC, GaN) to outperform the market:
 - · Leadership in high voltage power
 - Power module strategy including Si & SiC solutions



ST Silicon Carbide

Market Leadership and Supply Chain Excellence

Silicon Carbide: Exceeding our 2018 business targets

>\$100^M

SiC WW Revenues in 2018



#1 WW **Automotive** Supplier with SiC

Automotive Qualified Technology

Awards rate acceleration: More than 20 Car Makers engaged



8 European Car-Makers

Multiple models with ramp-up from 2019-20 onwards



ST teams are working with **Renault Nissan Mitsubishi Alliance** on several SiC
FET/Diodes projects



Working with **Hyundai Kia Motor Company** on several **SiC** FET/Diodes projects

ST Strategy and Execution

SiC supply chain **vertical integration Norstel**

ST acquired majority stake to secure an internal supply for SiC wafer substrates

Extended and secured supply chain capability through multi-year supply agreement with Cree-Wolfspeed

Keep expanding **6" Front-end** capacity in **ST Catania** plant with a second source planned

R&D execution: **Trench SiC** generation in qualification phase





Silicon Power Innovation

Electrification Opportunity Beyond Silicon Carbide

State-of-the-Art Battery Management up to 800V

Innovative cell monitoring architecture in cooperation with ~10 Chinese car makers and IMECAS as part of "China 2025" national program - Production start Q4 2019

Lithium cell monitoring



Devices per Vehicle



To support electro-mobility in China, targeting at least Mid-teen Share by 2021

Innovating on fast growing domains:

- IGBT: 2019 large projects ramping up with new Trench Technology - Projected ST CAGR '18-'23 > 30%
- Module business expanding at double digit YoY growth. ST innovating with expanding **ACEPACK™** product offer

already secured

In Electric Vehicles

Solution for Mild-Hybrid vehicle (48V)

48V dedicated Low Voltage Power **MOSFET**

Secured Business Awards

New VIPower™ intelligent power switches for Mild Hybrid vehicles: 48V Power Distribution and Motor Control

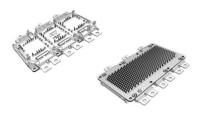
Targeting market leadership

The main technology pillars for mid-term ST growth



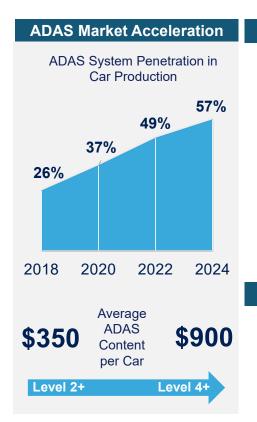
Agrate activation to fulfill awarded volumes in power electronics

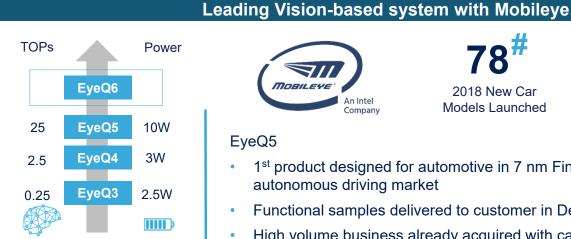
ACEPACKTM Family



Active Safety and Autonomous Driving

Several Developments to Increase ST Silicon Content in ADAS Systems









EyeQ System delivered by Mobileve to WW OEMs

EyeQ5

- 1st product designed for automotive in 7 nm FinFET suitable for both ADAS and autonomous driving market
- Functional samples delivered to customer in Dec 2018
- High volume business already acquired with car makers

Moving forward to autonomous vehicle with Auto-parking ability



- Advanced solution for mobility and autonomous parking
- Co-development leveraging ST expertise in designing safe and secure automotive SoCs and Panasonic leadership in image manipulation and system design
- 16 nm technology samples delivered

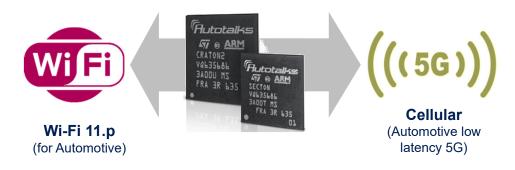


Source: Strategy Analytics Automotive Electronics System Demand Forecast, ST Internal

Connecting Vehicles

From Wi-Fi-based V2X to Dual Mode Wi-Fi & 5G -V2X

Market 1st dual-mode V2X solution to enable multi-standard connectivity



Market success of the partnership

Autotalks solution awarded for mass-production:

- 4 of the top 10 automakers plan to deploy our V2X solution
- Over 10 Tier1s awarded the chipset
- Start of Production by 2020



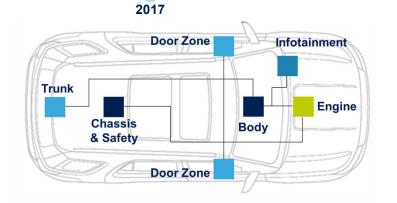




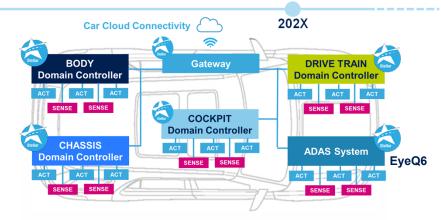
Car Digitalization: New Architectures

... Software Accounting for 30% of Vehicle Value by 2030

ST Technology enablers: FD-SOI 28nm with embedded Phase-Change Memory (PCM)







Distributed Architecture: 9k DMIPs per Car

- Local Control Units with up to 130 ECUs/Car (with 8-16-32-bit MCUs)
- Limited connectivity and in-vehicle data-flow (up to 10 Mbit/s)
- Heavy and expensive harness
- Extremely complex car Software management
- No car functionalities upgrade





Integrated Real-time Domain Architecture: 90kDMIPs per Car

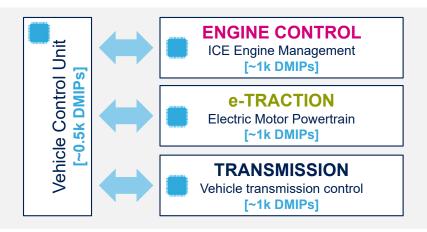
- ~5 Domain-Control Units with higher power computation
 - Stellar with multiple Arm® Cortex®-R52 cores embedded Phase-Change Memory (PCM)
- Autonomous Driving Super-computer (MPU ext. Memory) ~100 Trillion Operations per second
- · Architecture simplification, SW rationalization, harness drastic reduction
- Easy car functionality reconfiguration and SW upgrades
- High-speed in-vehicle communication
- Over-the-Air Software upgrade capability



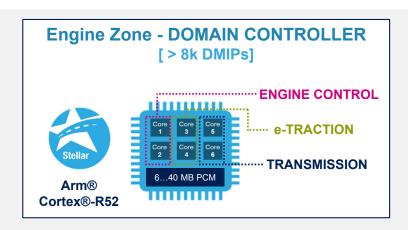


...from ECUs to Domain Controllers

Example: Evolution for Vehicle Traction







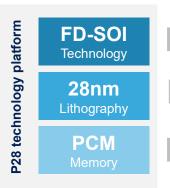
Requirements:

- High density technology
- Real-time
- Working Frequency > 400 MHz
- Low power consumption
- >16 MB of high speed access Non-Volatile Memory



Stellar: ST 28nm FD-SOI with embedded Phase-Change Memory

ST in-house production at Crolles 12"



Achieving Low Power Consumption requirement

Supporting Higher working Frequency (> 600 MHz)

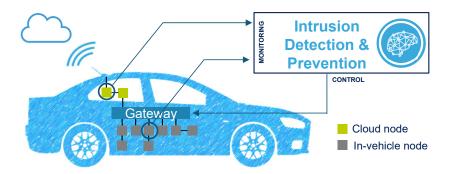
ST Phase-Change Memory (High-Speed High-Density robust embedded NVM)



- Samples delivered to leading customers currently running in vehicle testbeds
- > 10 running programs

ST Security Solutions for Automotive 28

A comprehensive portfolio for Vehicle Security



Hardware Security Cloud Connection TELEMACO In-Vehicle Connectivity

Artificial Intelligence and Neural Networks (NN) adopted for higher levels of security against cyber attacks

AI & NN Uses

- Learning about typical in-vehicle dataflows and big data exchange with the cloud
- Monitoring external connections and supervising internal node data-flow
- · Recognizing potential malicious cyber attack and activate antiintrusion strategy
- Early stage prevention on attack propagation

Adding Artificial Intelligence hardware acceleration to Stellar Family









Security Level

Secured communication Bandwidth

Industrial Applications – A Solid Base

ST Leadership in Power Solutions

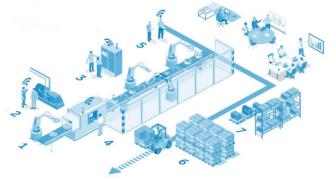
#2 In INDUSTRIAL DISCRETE



DISCRETE supplier in many INDUSTRIAL application domains

- Power tools
- Medical Diagnostic
- Security & Surveillance
- Networking system
- Building Safety systems
- ...

SMART FACTORY



SMART HOME



Automation

>15% Share LV MOS in High-End Industrial

Energy Management



HV MOS Super-junctions in Lighting & Power conversion

Motor Control



Share IGBT & IPM in **Home Appliances**



Source: IHS Industrial Semiconductor Market Tracker Q4 2018

Main Industrial Growth Drivers 30

Expanding ST Power Management leadership in **Server Farm** domain

x1.2

2019

2018

ST Volume Fcst. [Mu]

High Voltage Silicon MOSFETs MDmesh™ and SiC Rectifiers leveraging Increased demand of Cloudbased services (5G as enabler)

Power Silicon Value





Doubling **Battery Based** Application business

ST Volume Fcst. [Mu]



Low Voltage MOSFETs STripFET™ F7 & new F8 introduction; TVS Flat Package

Forklift Trucks & Power Tools market (steady growth at +6% CAGR FY'18-'23)

> Drones market (estimated \$100B in 2016-20)



Achieving Home Appliances efficiency with ST Smart Solutions





Outperforming market in Energy Industry

per Server/System



Flexible ACEPACKTM Module with IGBT, HV MOSFET & SiC as well as Ultrafast Rectifiers & High Voltage SCR addressing Markets with competitive trade-off between integration, cost and unsurpassed efficiency







Power & Energy

ST Volume Fcst. [Mu] x1.5

> 2018 2019

Motion Control

Increase ST share in Air-Con, White goods domain and Brown Goods (Induction Heating) with IPM SLLIMMTM, discrete IGBT, Ultrafast Rectifiers & "H series" Triacs







Intelligent Power Module (IPM)





Source: IHS Markit, ST Internal

Market Boost Supporting 5G migration

From Infrastructure to Personal Devices

Telecom Base Station

- Business Model: ST 8" technology development and manufacturing based on MACOM IP
- GaN on Silicon displacing LDMOS with significant cost advantage vs. competitor GaN on SiC solutions
- Engaged with major world wide market players
- Production Start: 2019. Volume ramp-up 2020

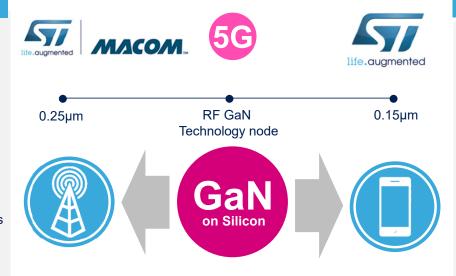
Targeting

>50%
Base Station Market

Share

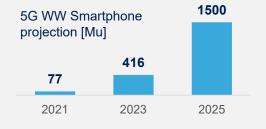
Capability to address





Mobile & Handset market

- ST licenses MACOM IP
- Targeting GaN on Silicon RF Power amplifiers for handset
- GaN on Silicon huge cost advantage vs traditional GaAs and competitors GaN on SiC grants an effective market penetration
- Engagements with market key players already initiated



2019

...scaling manufacturing capacity for these opportunities

2023



8 inch production

Supporting Production Volume for expected fast growth



Catania 8"+ Singapore 8" for flexibility and to support extra volume coming from Mobile

ADG is committed to **outperform** the market growth in **Automotive** and in **Discrete** application domains

- ADG is ready to support the mobility transformation, seizing market opportunities coming from electrification, shared mobility, automotive commitment to zero incidents, connectivity and vehicle architecture shifts
- Technology innovation, supported by world-class manufacturing, remains a priority to support new automotive trends, with a strong focus on new power materials (wide bandgap) and digital applications (FD-SOI and Phase Change Memory)
- ADG supports the growth of the company in non-automotive domains with technology leadership and an extended partnership network focusing on the Industrial domains and 5G applications

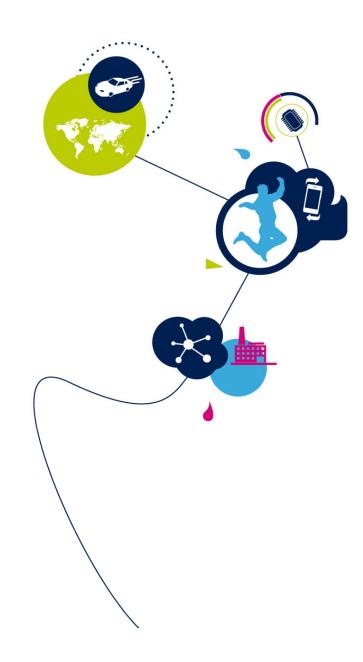


Analog, MEMS & Sensors

Benedetto Vigna

President
Analog, MEMS and Sensors Group (AMS)

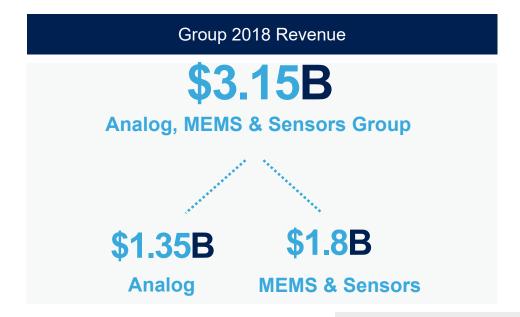


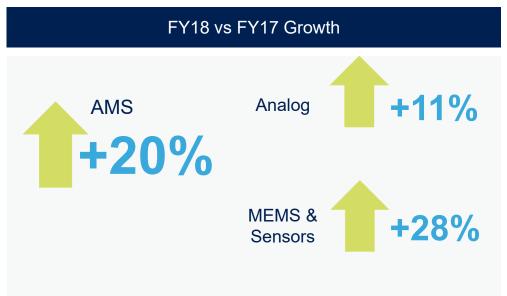




AMS Group at a Glance

Key Financial Data by Sub-Group





A wide range and diversified product portfolio to support a large customers base

70,000

Customers



AMS Strategy

MEMS & Sensors

- MEMS Sensors & Actuators
- Specialized Imaging Sensors

Analog

- General Purpose
- Application Specific

- Strategic focus on Industrial & Automotive end markets
- Address specific large opportunities in Personal Electronics
- Selective approach in Communications Equipment & Infrastructure focusing on advanced power management





MEMS Sensors & Actuators

Technology Focus



Thin Film Piezoelectric PETRA*

- · Innovative piezoelectric materials
- Higher efficiency
- Lower cost



Microactuators for Ink Jet printing, Speakers & Infrared Scanners

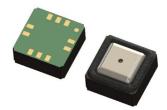


Next Generation ThELMA*

- · Higher accuracy and reliability
- Ultra-low power
- More intelligence



Motion sensors for Personal Electronics, Automotive & Industrial



Next Generation BASTILLE*

- Higher accuracy
- Size reduction
- Waterproofing

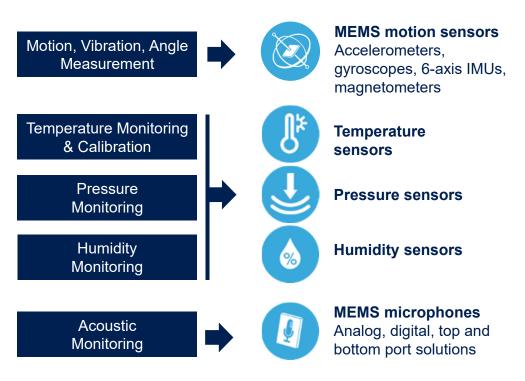


Environmental sensors for Personal Electronics & Industrial

*ST proprietary MEMS technologies.

MEMS Sensors 37

Higher Accuracy for Industrial & Automotive





Inclinometer





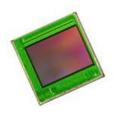
Hi-g accelerometers for airbags





Specialized Imaging Sensors

Technology Focus



Structured Light

- Global Shutter
- High Quantum Efficiency
- 3D-BSI



Time of Flight (ToF)

- Direct & indirect
- Increasing resolution
- All-in-one & low power
- · Multi-zone & multi-object capability
- 3D-BSI, 40 nm SPAD



Ambient Light Sensor

- High sensitivity
- Small size & low power
- Flicker detection

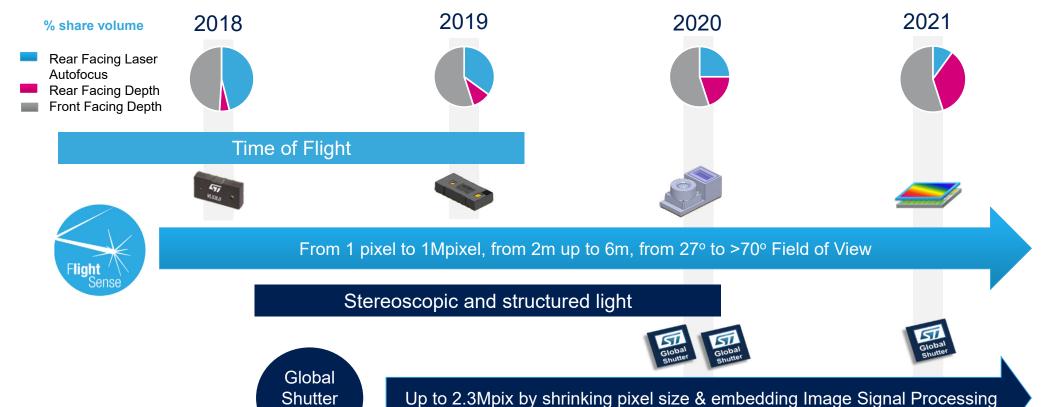
3D Sensing for smartphones (Front facing and rear facing) and automotive (LiDAR & in cabin)

Proximity and ranging Sensors for Personal Electronics and Industrial

> Low-cost spectrometers for home & building automation







Sensor

Source: ST Estimates

Diversifying our Imaging Offer

for Automotive



Sensing & Viewing Camera

Rolling Shutter

- High Dynamic Range (HDR)
- · Low Noise
- High Sensitivity
- FSI

- Flicker Free
- No Memory
- Low Noise
- High Sensitivity
- BSI



In-Cabin Optical Sense

Global Shutter

- HDR
- Low Noise
- High sharpness
- Multi-zone
- FSI



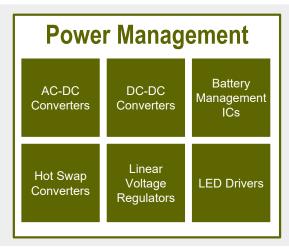
LiDAR

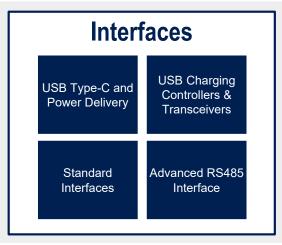
F**light**Sense™

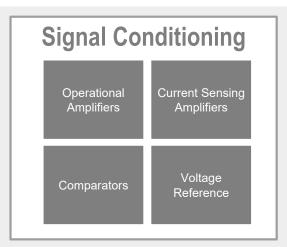
- integrated SoC receiver solution
- 40 nm & 3D CMOS
- SPAD



Analog – General Purpose 41

















Focus Areas

Motion Control

3D Printers

Industrial Drives

Pumps & Compressors



Factory



City



Home & Building

Energy Management



Power Management



Metering



Wireless Charging

Product Leadership

Motor **Drivers**



Intelligent Power **Switches**

Powerline Communication ICs



Leveraging Technology & IP, System knowhow, Customer intimacy



Smart Motor Control

Broad portfolio with more than 130 products and more than One Billion Units sold









Based on **Advanced BCD** Technology

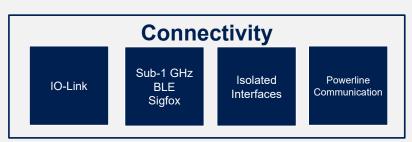


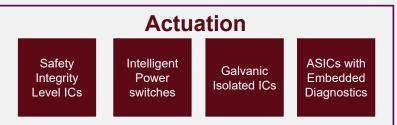




Factory Automation







- Communication and flexibility to adapt in real-time to external events
- Robustness and reliability thanks to embedded intelligence and diagnostics
- Higher efficiency and safety at all points in power usage
- Distributed intelligence, decentralized diagnostics











IO-Link



Powerline Communication







Based on BCD, BiCMOS, Galvanic Isolation

Power & Energy Management

Smart Grid, Smart Metering & Smart Solar

- > 100 million meters in the field
- Powerline Communication technology leadership
- System knowhow and partnership with key players





Advanced Drivers & System-in-Package

- Driving MOSFETs, IGBTs wide bandgap FETs
- Galvanic isolation for safety certification
- High voltage, high power-density, high speed







Power Management for Data Centers & 5G

- Digital power control
- Galvanic isolation
- Advanced drivers & SiP for power actuation









Based on **BCD**, **Galvanic Isolation**



AMS Takeaways

MEMS & Sensors

MEMS

6-axis iNEMO™ IMU

with Machine Learning Core

Specialized Imaging
Sensors

World's smallest multispectral sensor RGB-UV-IR with Light Flicker engine



Analog

General Purpose

Off-line high-voltage converters for rugged and flexible 5-30V power supplies



577

Application Specific

Galvanic isolated smart power switch safety and robustness for Industry 4.0



57

A wide range and diversified product portfolio to support a large customers base Serving more than 70,000

Customers

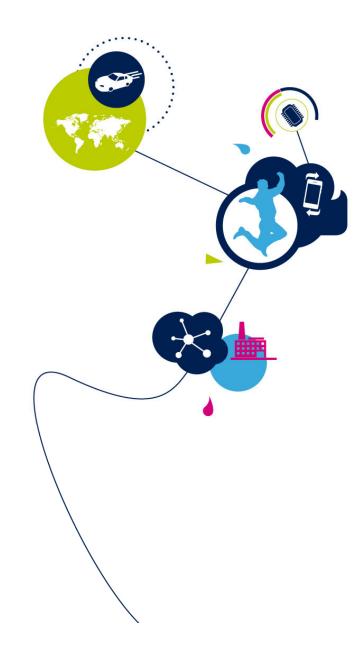


Microcontrollers & Digital ICs

Claude Dardanne

President
Microcontrollers & Digital ICs Group (MDG)







MDG Group at a Glance

Key Financial Data by Sub-Group





MMS Microcontrollers & Memories

Digital Digital and Mixed ASICs, Aerospace,
Defense and mmW Communication



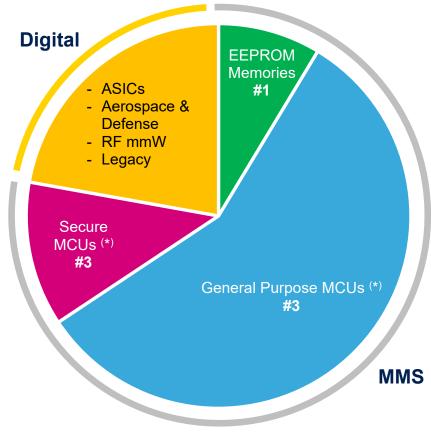
Microcontrollers & Digital Group

2018 revenues split

- ~ 70% Revenues with Microcontrollers (*)
- ~ 20% Revenues with Digital products
- ~ 10% Revenues with EEPROM memories

3 year target

- Leadership on Embedded Processing (*)
- Apply Digital competences to Industrial (MPU / AI) & RF mmW, capitalizing on ST differentiated technologies & IP
- · Consolidate leadership in EEPROM Memories

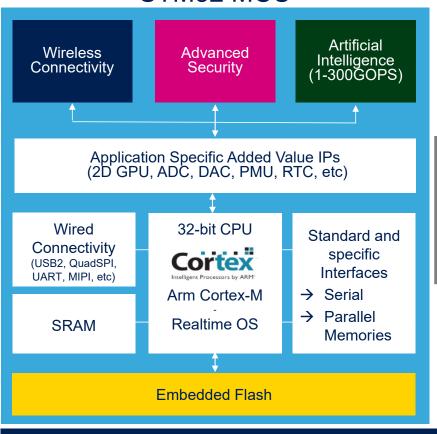






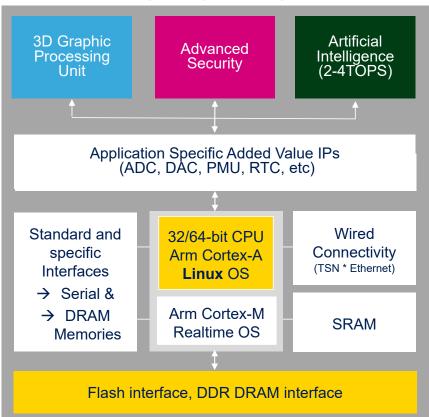
STM32 Pervasion

STM32 MCU



More
Computing
Power and
faster
external
Memory
Access

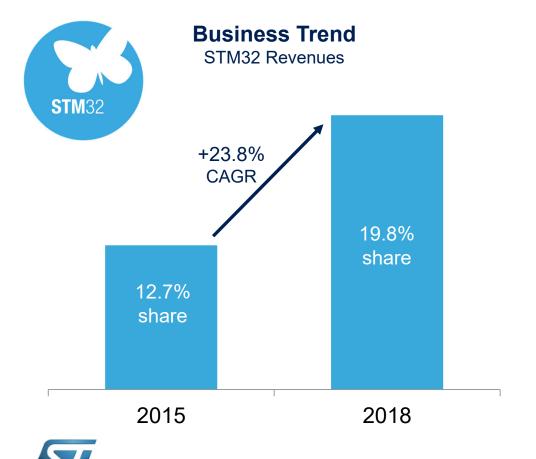
STM32 MPU



Expanded Ecosystem

TSN: Time sensitive networking

STM32 Market Expansion



14 Product Series (>1000 Part Numbers)

Ultra Low Power MCU

Proliferation: L0, L1, L4

New: STM32L5 with secure Arm Cortex-M33 core

Mainstream MCU

Proliferation: F0, F1, F3

New: G0 entry level, G4 enhanced mixed signal

High Performance MCU

Proliferation: F2, F4, F7, H7

New: STM32MP1 microprocessor product

Wireless MCU

New: STM32WB BLE 5.0, Zigbee, Thread

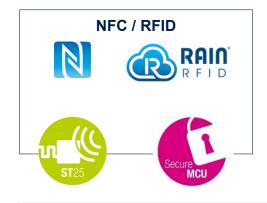
Enhanced ecosystem

Expanded STM32CubeMX

New: AI with STM32Cube.AI

STM32 Wireless Connectivity

From Near Field Communication to Cellular







From 10 kbps to 72 Mbps

Very short range secured

Industrial

Logistics

Personal Electronics

Mobile payment

Automotive

- Wireless charging
- Secure access

Low power long range networks

Industrial

- Remote monitoring
- Smart agriculture

Personal Electronics

Direct cloud access

Ultra-low power Short-Medium range

Industrial

- Building automation
- Process automation

Personal Electronics

- Wearables
- Home connectivity





Artificial Intelligence on the STM32 53

An extensive SW toolbox to support easy creation of AI applications







Function packs quick prototyping



Audio & motion analysis Character recognition Image classification









www.st.com/STM32CubeAl



STM32 Security

A Scalable Offer





Secure MCU ST31/33 ST53/54



Application Specific Security





STM32 MCU STSAFE secure element



Secure Authentication Secure boot & Security services



STM32 with Trust Zone L5 with Cortex-M33



Secure execution



Code/Data isolation



STM32 with Crypto Engine F2/F4/F7/H7 L4/L4+/L5



Secure connectivity

SW Protection



STM32 with Memory Protection F1-F7/L0-L4

SW & memory protection

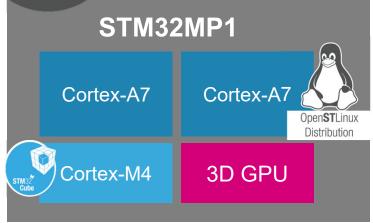


Several security features available across all products: unique ID, tamper detection, write & integrity memory protection



STM32MP1 General Purpose MPU

Accelerating IoT and Smart Industry Innovation



- Multicore Microprocessor running RTOS & Linux in parallel
- Suitable for industrial applications with 10-year longevity commitment



- Heterogeneous architecture (2xMPU+MCU+GPU Cores)
- STM32Cube full ecosystem reuse on Arm Cortex-M4 core
- Dual Cortex-A7 with free Linux Distribution: OpenSTLinux



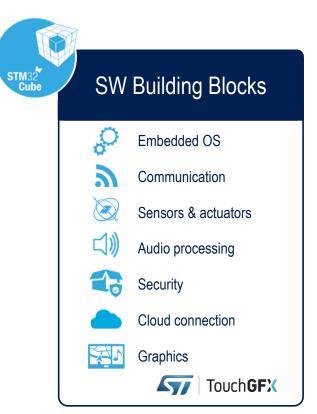


Expanding the STM32 Ecosystem

Enabling more than 60,000 Customers











Certified Security Solutions 57

Banking & ID



Hardware & Solutions for Banking, ID, PayTV, **Transport**

> ST31 **STPay** ST53

Wearables

Mobile Security Consumer



Hardware & Solutions for **Mobile Transactions** (Consumer)

> ST33 eSIM, eSE ST21NFC

> > ST54



Authentication



Solutions for **Brand Protection, Computer, IoT**

> STSAFE-A STSAFE-J STSAFE-TPM Custom

M2M & Auto



Hardware & Solutions for M₂M

Automotive eSIM & eSE



Industrial

ST32H-E/I, ST32-M ST33-M ST33-A **Incard Solution**



Mobile Security Solutions 58

- Volume pervasion for ST eSIM secure solutions
- Deployment of ST Secure Element + NFC controller SoC solution
- Further integration through NFC / eSE / eSIM convergence into a single die

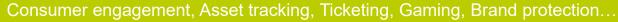






Short-range Connectivity

NFC RF EEPROM Portfolio





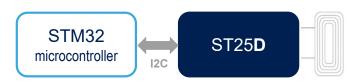




Industrial, Lighting, Consumer, Metering, Appliance, Healthcare, ...





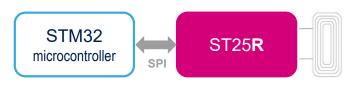




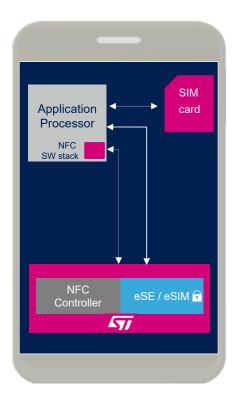
POS & mPOS Terminals, Automotive, Access control, Gaming, ...















Short Range Connectivity

60 GHz RF Transceiver

High-speed, low-power wireless link for close proximity data transmission









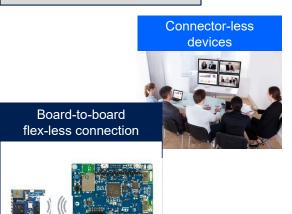
ST60-A2
6 Gbps

ST60-A3
6 Gbps
Full Duplex

USB-C, DisplayPort

- Very low power solution: power budget of 40 mW
- Miniature form factor with optimized BoM

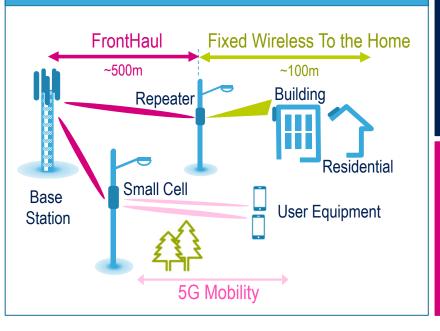






The 5G Disruption 61

5G mmW Network Infrastructure



- Very high data rate x100^{*}
- Reduced latency 5 times lower*
- Very high reliability 99.999%
- Connections of **billions** of nodes
- Improved coverage

* vs 4G

- New architecture with denser network (small cells)
- New technologies: Advanced beam forming, massive MiMo
- New spectrum: Use of millimeter waves

ST Strengths

Wide range of **RF technology** solutions

BiCMOS, CMOS, FD-SOI, RF-SOI

High performance mmW RF solutions for 10+ years

RF Transceiver products up to 60 GHz

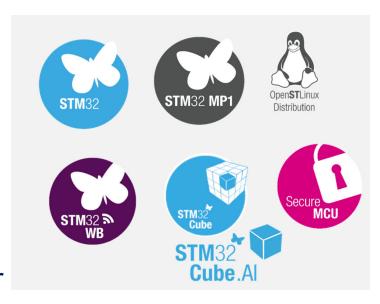
Pioneered beamforming solutions for Satcom market

RF Front-end (PA, LNA), Transceiver & Beamforming products



Takeaways

- Assets to further improve leadership position in Embedded Processing
 - More Computing power
 - More Connectivity
 - More Security
 - More Al capabilities
 - Advanced Ecosystem
- Focus on Industrial market as a key growth driver
- Assets to enter the mmW & 5G markets
 - Adapted technology solutions
 - High performance RF transceiver product
 - Beamforming solutions





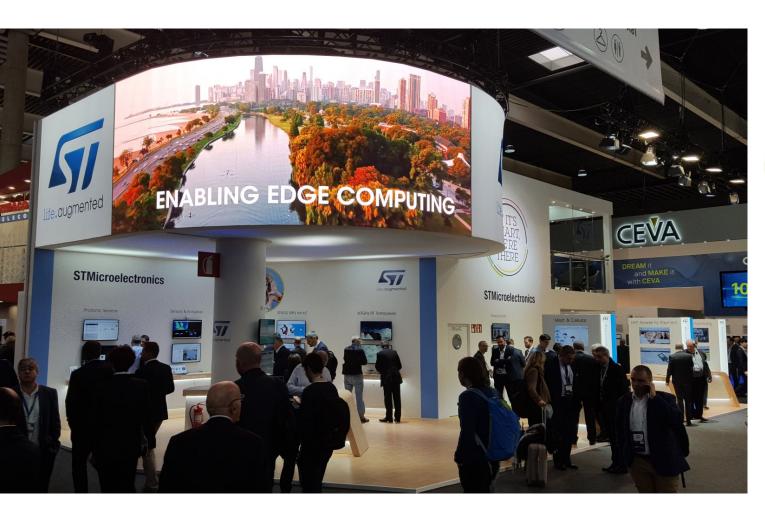




Questions & Answers



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25-28 February 2019